

6A High-Speed MOSFET Drivers

Features

- Latch-Up Protected: Will Withstand >1.5A Reverse Output Current
- Logic Input: Will Withstand Negative Swing Up To 5V
- . ESD Protected: 4 kV
- · Matched Rise and Fall Times:
 - 25 ns (2500 pF load)
- · High Peak Output Current: 6A
- · Wide Input Supply Voltage Operating Range:
 - 4.5V to 18V
- High Capacitive Load Drive Capability: 10,000 pF
- Short Delay Time: 55 ns (typ.)
- CMOS/TTL-Compatible Input
- Low Supply Current With Logic '1' Input:
 - 450 μA (typ.)
- Low Output Impedance: 2.5Ω
- Output Voltage Swing to Within 25 mV of Ground or V_{DD}
- · Wide Operating Temperature Range:
 - -55°C to +125°C
- See TC4420/TC4429 Data Sheet (DS21419) for additional temperature range and package offerings.

Applications

- Switch-mode Power Supplies
- Motor Controls
- Pulse Transformer Driver
- Class D Switching Amplifiers

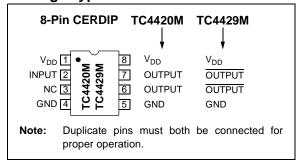
General Description

The TC4420M/TC4429M are 6A (peak), single-output MOSFET drivers. The TC4429M is an inverting driver (pin-compatible with the TC429M), while the TC4420M is a non-inverting driver. These drivers are fabricated in CMOS for lower power and more efficient operation versus bipolar drivers.

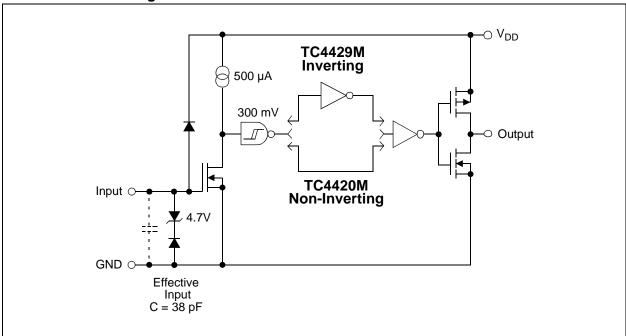
Both devices have TTL/CMOS-compatible inputs, which can be driven as high as $V_{DD} + 0.3V$ or as low as -5V without upset or damage to the device. This eliminates the need for external level-shifting circuitry and its associated cost and size. The output swing is rail-to-rail, ensuring better drive voltage margin, especially during power-up/power-down sequencing. The propagational delay time is only 55 ns (typ.), while the output rise and fall times are only 25 ns (typ.) into 2500 pF across the usable power supply range.

Unlike other drivers, the TC4420M/TC4429M are virtually latch-up proof. They replace three or more discrete components, saving PCB area and parts while improving overall system reliability.

Package Types:



Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Supply Voltage+20V Input Voltage-5V to V_{DD} + 0.3V Input Current (V_{IN} > V_{DD})......50 mA

† Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, $T_A = +25^{\circ}C$ with $4.5V \le V_{DD} \le 18V$.									
Parameters	Sym	Min	Тур	Max	Units	Conditions			
Input									
Logic '1', High Input Voltage	V_{IH}	2.4	1.8	_	V				
Logic '0', Low Input Voltage	V_{IL}	_	1.3	0.8	V				
Input Voltage Range	V _{IN}	- 5	_	V _{DD} + 0.3	V				
Input Current	I _{IN}	-10	_	+10	μΑ	$0V \le V_{IN} \le V_{DD}$			
Output									
High Output Voltage	V_{OH}	V _{DD} – 0.025		_	V	DC TEST			
Low Output Voltage	V_{OL}	_	_	0.025	V	DC TEST			
Output Resistance, High	R _{OH}	_	2.1	2.8	Ω	I _{OUT} = 10 mA, V _{DD} = 18V			
Output Resistance, Low	R _{OL}	_	1.5	2.5	Ω	I _{OUT} = 10 mA, V _{DD} = 18V			
Peak Output Current	I_{PK}	_	6.0	_	Α	V _{DD} = 18V			
Latch-Up Protection Withstand Reverse Current	I _{REV}	_	> 1.5	_	Α	Duty cycle ≤ 2%, t ≤ 300 μs			
Switching Time (Note 1)									
Rise Time	t _R	_	25	35	ns.	Figure 4-1 , C _L = 2,500 pF			
Fall Time	t _F	_	25	35	ns.	Figure 4-1 , C _L = 2,500 pF			
Delay Time	t _{D1}	_	55	75	ns.	Figure 4-1			
Delay Time	t _{D2}	_	55	75	ns.	Figure 4-1			
Power Supply									
Power Supply Current	I _S	_	0.45	1.5	mA	V _{IN} = 3V			
		_	55	150	μΑ	V _{IN} = 0V			
Operating Input Voltage	V_{DD}	4.5		18	V				

Note 1: Switching times ensured by design.

DC CHARACTERISTICS (OVER OPERATING TEMPERATURE RANGE)

Electrical Specifications: Unless otherwise noted, over operating temperature range with $4.5V \le V_{DD} \le 18V$.								
Parameters	Sym	Min	Тур	Max	Units	Conditions		
Input								
Logic '1', High Input Voltage	V_{IH}	2.4	_	_	V			
Logic '0', Low Input Voltage	V _{IL}	_	_	0.8	V			
Input Voltage Range	V _{IN}	-5	_	$V_{DD} + 0.3$	V			
Input Current	I _{IN}	-10	_	+10	μA	$0V \le V_{IN} \le V_{DD}$		
Output								
High Output Voltage	V _{OH}	V _{DD} – 0.025	_	_	V	DC TEST		
Low Output Voltage	V _{OL}	_	_	0.025	V	DC TEST		
Output Resistance, High	R _{OH}	_	3	5	Ω	I _{OUT} = 10 mA, V _{DD} = 18V		
Output Resistance, Low	R _{OL}	_	2.3	5	Ω	I _{OUT} = 10 mA, V _{DD} = 18V		
Switching Time (Note 1)								
Rise Time	t _R	_	32	60	ns.	Figure 4-1 , C _L = 2,500 pF		
Fall Time	t _F	_	34	60	ns.	Figure 4-1 , C _L = 2,500 pF		
Delay Time	t _{D1}	_	50	100	ns.	Figure 4-1		
Delay Time	t _{D2}	_	65	100	ns.	Figure 4-1		
Power Supply								
Power Supply Current	I _S	_	0.45	3	mA	V _{IN} = 3V		
		_	60	400	μΑ	$V_{IN} = 0V$		
Operating Input Voltage	V_{DD}	4.5	_	18	V			

Note 1: Switching times ensured by design.

TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, all parameters apply with 4.5V ≤ V _{DD} ≤ 18V.								
Parameters	Sym	Min	Тур	Max	Units	Conditions		
Temperature Ranges								
Specified Temperature Range (M)	T _A	-55	_	+125	°C			
Maximum Junction Temperature	TJ	_	_	+150	°C			
Storage Temperature Range	T _A	-65	_	+150	°C			
Package Thermal Resistances								
Thermal Resistance, 8L-CERDIP	θ_{JA}	_	150	_	°C/W			

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, $T_A = +25^{\circ}C$ with 4.5V $\leq V_{DD} \leq 18V$.

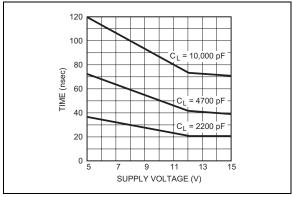


FIGURE 2-1: Rise Time vs. Supply Voltage.

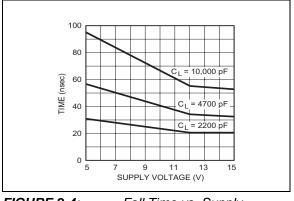


FIGURE 2-4: Fall Time vs. Supply Voltage.

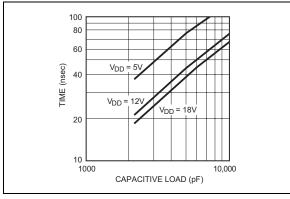


FIGURE 2-2: Rise Time vs. Capacitive Load.

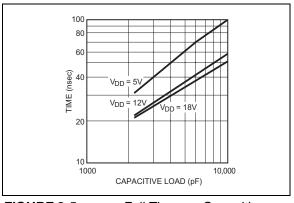


FIGURE 2-5: Fall Time vs. Capacitive Load.

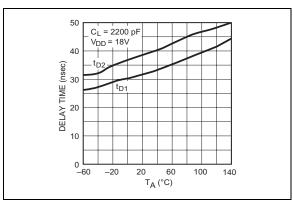


FIGURE 2-3: Propagation Delay Time vs. Temperature.

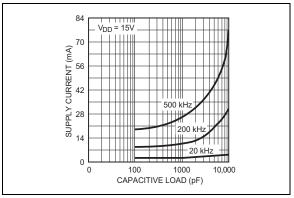


FIGURE 2-6: Supply Current vs. Capacitive Load.

Note: Unless otherwise indicated, $T_A = +25^{\circ}C$ with $4.5V \le V_{DD} \le 18V$.

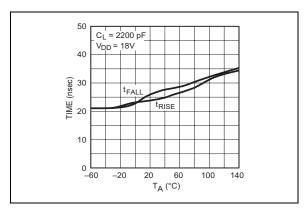


FIGURE 2-7: Temperature.

Rise and Fall Times vs.

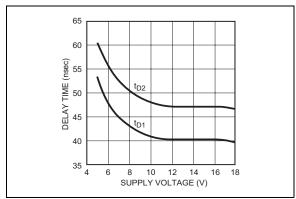


FIGURE 2-8: Supply Voltage.

Propagation Delay Time vs.

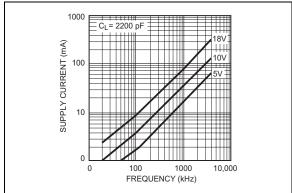
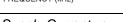


FIGURE 2-9: Frequency.

Supply Current vs.



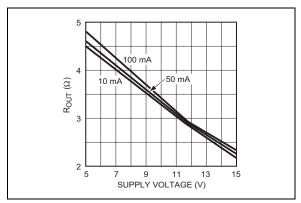


FIGURE 2-10: High-State Output Resistance vs. Supply Voltage.

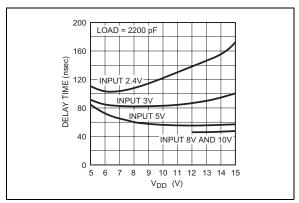


FIGURE 2-11: Effect of Input Amplitude on Propagation Delay.

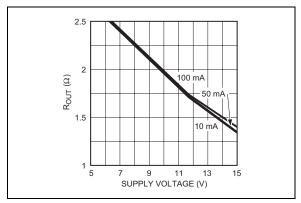
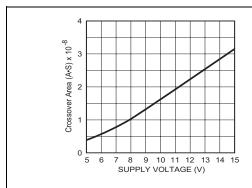


FIGURE 2-12: Low-State Output Resistance vs. Supply Voltage.

Note: Unless otherwise indicated, $T_A = +25^{\circ}C$ with $4.5V \le V_{DD} \le 18V$.



* The values on this graph represent the loss seen by the driver during one complete cycle. For a single transition, divide the value by 2.

FIGURE 2-13: Crossover Energy*.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin No. 8-Pin CERDIP	Symbol	Description				
1	V _{DD}	Supply input, 4.5V to 18V				
2	INPUT	Control input, TTL/CMOS compatible input				
3	NC	No Connection				
4	GND	Ground				
5	GND	Ground				
6	OUTPUT	CMOS push-pull output				
7	OUTPUT	CMOS push-pull output				
8	V_{DD}	Supply input, 4.5V to 18V				

3.1 Supply Input (V_{DD})

The V_{DD} input is the bias supply for the MOSFET driver and is rated for 4.5V to 18V with respect to the ground pins. The V_{DD} input should be bypassed to ground with a local ceramic capacitor. The value of the capacitor should be chosen based on the capacitive load that is being driven. A minimum value of 1.0 μ F is suggested.

3.2 Control Input

The MOSFET driver input is a high-impedance, TTL/CMOS-compatible input. The input circuitry of the TC4420M/TC4429M MOSFET driver also has a "speed-up" capacitor. This helps to decrease the propagation delay times of the driver. Because of this, input signals with slow rising or falling edges should not be used, as this can result in double-pulsing of the MOSFET driver output.

3.3 CMOS Push-Pull Output

The MOSFET driver output is a low-impedance, CMOS, push-pull style output capable of driving a capacitive load with 6.0A peak currents. The MOSFET driver output is capable of withstanding 1.5A peak reverse currents of either polarity.

3.4 Ground

The ground pins are the return path for the bias current and the high peak currents that discharge the load capacitor. The ground pins should be tied into a ground plane or have very short traces to the bias supply source return.

4.0 APPLICATIONS INFORMATION

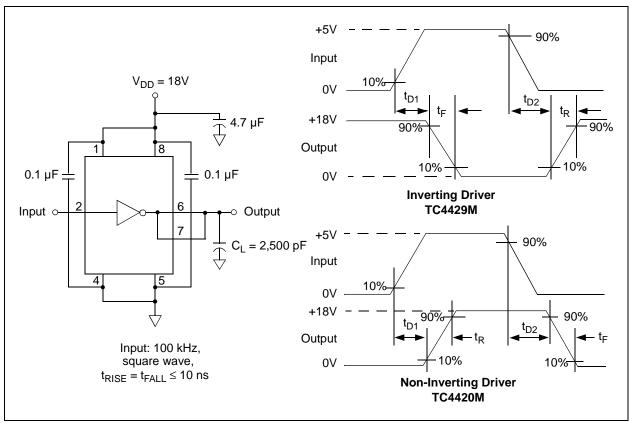
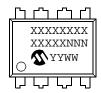


FIGURE 4-1: Switching Time Test Circuits.

5.0 PACKAGING INFORMATION

5.1 Package Marking Information

8-Lead CERDIP (300 mil)





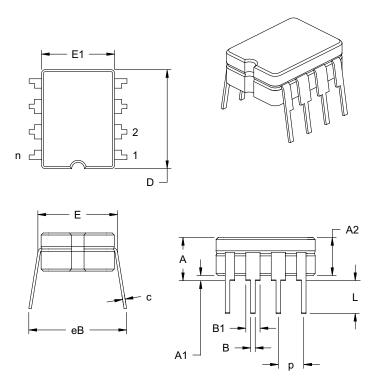


Legend: XX...X Customer-specific information
Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
NNN Alphanumeric traceability code

© Pb-free JEDEC designator for Matte Tin (Sn)
* This package is Pb-free. The Pb-free JEDEC designator (©3)
can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

8-Lead Ceramic Dual In-line - 300 mil (CERDIP)



		INCHES*		MILLIMETERS			
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.160	.180	.200	4.06	4.57	5.08
Standoff §	A1	.020	.030	.040	0.51	0.77	1.02
Shoulder to Shoulder Width	E	.290	.305	.320	7.37	7.75	8.13
Ceramic Pkg. Width	E1	.230	.265	.300	5.84	6.73	7.62
Overall Length	D	.370	.385	.400	9.40	9.78	10.16
Tip to Seating Plane	L	.125	.163	.200	3.18	4.13	5.08
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.055	.065	1.14	1.40	1.65
Lower Lead Width	В	.016	.018	.020	0.41	0.46	0.51
Overall Row Spacing	eВ	.320	.360	.400	8.13	9.15	10.16

*Controlling Parameter

JEDEC Equivalent: MS-030

Drawing No. C04-010

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (February 2005)

• Original Release of this Document.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

Examples: PART NO. TC4420MJA: 6A High-Speed MOSFET Device and Temperature Package Driver, Non-inverting, Range 8LD CERDIP package. Device and TC4420M: 6A High-Speed MOSFET Driver, Non-Inverting, TC4429MJA: 6A High-Speed MOSFET Temperature Range: -55°C to +125°C TC4429M: 6A High-Speed MOSFET Driver, Inverting, Driver, Inverting, -55°C to +125°C 8LD CERDIP package. JA = Ceramic Dual In-line (300 mil Body), 8-lead Package:

NOTES:

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